

0083-0865-2

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

Masashi GOTOH, et al. ✓

SERIAL NO.: 09/119,626 ✓

FILED: July 21, 1998 ✓

FOR: CIRCUIT BOARD HAVING
BONDING AREAS TO BE
JOINED WITH BUMPS BY
ULTRASONIC BONDING

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EXAMINER: CUNEO, K.

GROUP ART UNIT: 2841



AMENDMENT AFTER FINAL UNDER 37 CFR 1.116

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

In response to the Official Action dated August 29, 2000, please amend the above-
identified application as follows:

IN THE SPECIFICATION

Please amend the specification as follows:

Page 1, line 24, change "making free use of related art totally" to --of the prior art--.

IN THE CLAIMS

Please cancel Claims 4-6, 8, and 10-12 without prejudice or disclaimer.

Please amend the following claims:

7. (Once Amended) A circuit board [for mounting a part having a plurality of bumps
by ultrasonic bonding, said circuit board] comprising:

RECEIVED
DEC 28 2000
TC 2800 MAIL ROOM

2/7/01 ✓

Do Not Enter
9/9/01

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